

*Attorney Docket No.: 42.P18072*  
*Application No.: 10/735,121*  
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***IN THE SPECIFICATION:***

Please replace paragraph [0027] with the following amended paragraph:

[0027] Fig. 3 is a top view of channels 140 in one of heat exchange layer 130 (in device 100 in Fig. 1A) or integrated circuit chip 110 (in device 100' in Fig. 1B) according to another example implementation consistent with the principles of the invention. In contrast to Fig. 2, integrated circuit chip 110 in Fig. 3 may have three or more areas having different power densities. Area 310 may be assumed to have the highest power density, followed in order by area ~~310~~ 330 and area 320 that has the lowest.